

N-Channel Super Junction Power MOSFET III

General Description

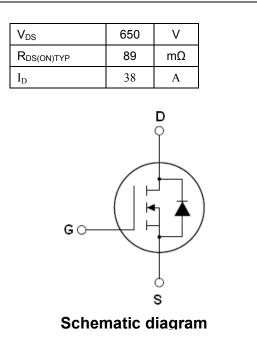
The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge



♦ Intrinsic fast-recovery body diode



Package Marking And Ordering Information

Device	Device Package	Marking
NCE65TF099T	TO-247	NCE65TF099T

TO-247

Table 1. Absolute Maximum Ratings ($T_c=25^{\circ}C$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	Vds	650	V
Gate-Source Voltage (VDs=0V) AC (f>1 Hz)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	38	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	24	A
Pulsed drain current (Note 1)	I _{DM (pluse)}	152	А
Maximum Power Dissipation(Tc=25°C)	PD	322	W
Derate above 25°C		2.58	W/°C
Single pulse avalanche energy (Note 2)	Eas	841	mJ
Avalanche current ^(Note 1)	I _{AR}	7	А
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	3.9	mJ



NCE65TF099T

Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leqslant 480 V$,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leqslant 480 V, I_{SD} < I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55+150	°C

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.39	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states				•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =500µA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			3	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =19A		89	109	mΩ
Dynamic Characteristics						
Input Capacitance	Clss			2800	3200	pF
Output Capacitance	Coss	- V _{DS} =50V,V _{GS} =0V, F=1.0MHz		97		pF
Reverse Transfer Capacitance	Crss			1.5		pF
Total Gate Charge	Qg)/ _400)// _204		45	55	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =38A, V _{GS} =10V		15		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		11.5		nC
Switching times						
Turn-on Delay Time	t _{d(on)}			16		nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =19A,		13		nS
Turn-Off Delay Time	t _{d(off)}	R _G =1.7Ω,V _{GS} =10V		71		nS
Turn-Off Fall Time	t _f			13		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I _{SD}	T -25%0			38	А
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			152	А
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =28A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}			180		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =19A,di/dt=100A/µs		1.6		uC
Peak Reverse Recovery Current	I _{rrm}			18		А

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25\Omega



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

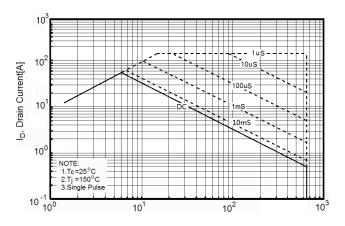


Figure3. Source-Drain Diode Forward Voltage

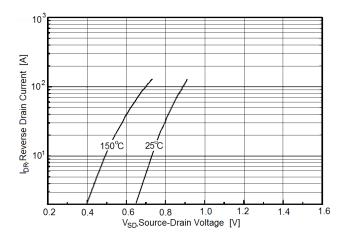


Figure5. Transfer characteristics

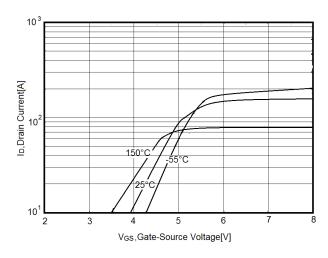
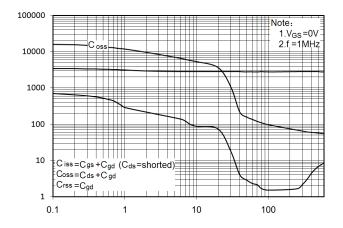
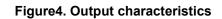


Figure2. Capacitance





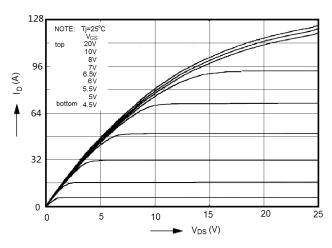


Figure6. Static drain-source on resistance

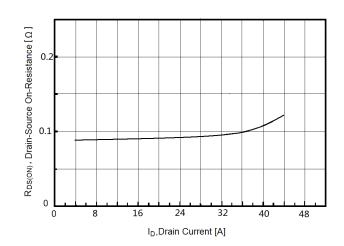
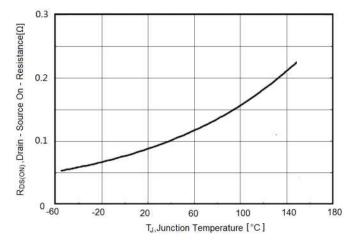






Figure7. R_{DS(ON)} vs Junction Temperature

Figure8. BV_{DSS} vs Junction Temperature



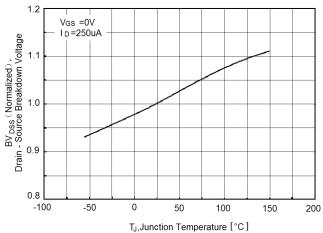
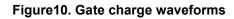
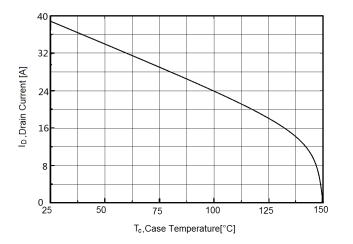


Figure9. Maximum I_D vs Junction Temperature



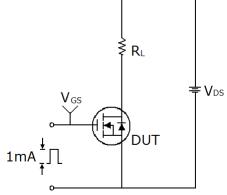


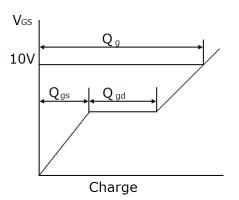
12 V_{GS},Gate - Source Voltage [V] 10 8 0.8V_{DS} max 6 4 2 Note: ID= 38 A 0 10 0 20 30 40 50 Q_G, Total Gate Charge [nC]



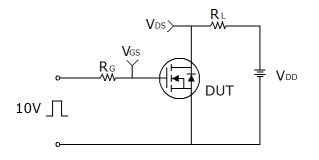
Test circuit

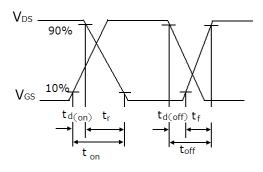
1) Gate charge test circuit & Waveform



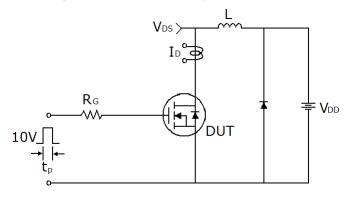


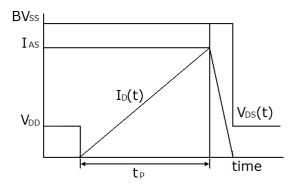
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

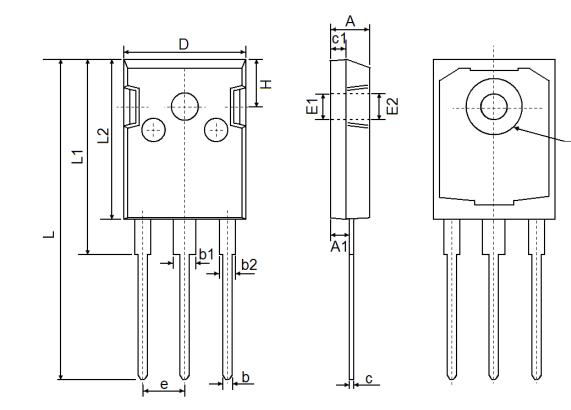




Φ



TO-247 Package Information



Symbol -	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.850	5.150	0.191	0.200	
A1	2.200	2.600	0.087	0.102	
b	1.000	1.400	0.039	0.055	
b1	2.800	3.200	0.110	0.126	
b2	1.800	2.200	0.071	0.087	
С	0.500	0.700	0.020	0.028	
c1	1.900	2.100	0.075	0.083	
D	15.450	15.750	0.608	0.620	
E1	3.500 REF		0.138 REF		
E2	3.600 REF		0.142 REF		
L	40.900	41.300	1.610	1.626	
L1	24.800	25.100	0.976	0.988	
L2	20.300	20.600	0.799	0.811	
Ф	7.100	7.300	0.280	0.287	
е	5.450 TYP		0.215	5 TYP	
Н	5.980 REF		0.235	5 REF	



ATTENTION:

- Any and all NCE products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE representative nearest you before using any NCE products described or contained herein in such applications.
- NCE assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE products described or contained herein.
- Specifications of any and all NCE products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE Power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE Power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE product that you intend to use.
- This catalog provides information as of Mar. 2010. Specifications and information herein are subject to change without notice.